



## Technical Capability

# 3

## Capability

Item	English Unit	Metric Unit
Panel Size	20x40 ( " )	508x1016 (mm)
Max Layers	20	20
Thickness	0.00394-0.236 ( " )	0.1-6 (mm)
Min Hole Size	0.0059 ( " )	0.15 (mm)
Aspect Ratio	20:01	20:01
Width/Gap	1.5/1.5 (mil)	0.0381/0.0381 (mm)
Impedance Control	+/- 5%	+/- 5%
In/Out Base Copper Thickness	10/10 (oz)	10/10 (oz)
Plating Thick Gold	Au 0.8-60 (μ " )	Au 0.02-1.524 (μm)
	Ni 50-300 (μ " )	Ni 1.27-7.62 (μm)
Immersion Gold	Au 0.8-10 (μ " )	Au 0.02-0.254 (μm)
	Ni 50-300 (μ " )	Ni 1.27-7.62 (μm)
Soldermask Thickness	0.2-1.2 (mil)	5.08-30.48 (μm)
Peelable Thickness	4-20 (mil)	101.6-508 (μm)